

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"6608389" or "6521978"	USPAT	OR	OFF	2005/02/04 12:22
S2	890	257/796	USPAT	OR	OFF	2005/06/17 18:12
S3	1	"6246115".PN.	USPAT	OR	OFF	2004/06/15 17:27
S4	1	"6316822".PN.	USPAT	OR	OFF	2004/06/15 17:28
S5	1	"6429513".PN.	USPAT	OR	OFF	2004/06/15 17:28
S6	1	"6472743".PN.	USPAT	OR	OFF	2004/06/15 17:28
S7	1	"6507107".PN.	USPAT	OR	OFF	2004/06/15 17:28
S8	1	"6507107".PN.	USPAT	OR	OFF	2004/06/15 17:29
S9	1	"6528882".PN.	USPAT	OR	OFF	2004/06/15 17:29
S10	0	"2002/0079567".PN.	USPAT	OR	OFF	2004/06/15 17:29
S11	0	"2002/0185734".PN.	USPAT	OR	OFF	2004/06/15 17:29
S12	0	"2003/0047798".PN.	USPAT	OR	OFF	2004/06/15 17:29
S13	0	"2003/0057545".PN.	USPAT	OR	OFF	2004/06/15 17:29
S14	2015	257/706	USPAT	OR	OFF	2004/11/23 22:22
S15	16	"6475830".pn. "6392896".pn. "6335221".pn. "6297551".pn. "6239482".pn. "6208525".pn. "6157080".pn. "6075289".pn. "6069793".pn. "5999437".pn. "5986886".pn. "5872700".pn. "5872051".pn. "5807791".pn. "5784264".pn. "5642262".pn.	USPAT	OR	OFF	2004/09/30 15:49
S16	2	"20020074669".pn. or "20020017721".pn.	US-PGPUB; USPAT	OR	OFF	2004/09/30 15:50
S17	1	"20020195704"	US-PGPUB; USPAT	OR	OFF	2004/11/23 21:17
S18	2542	257/706	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 12:51
S19	1252	257/796	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/23 22:35
S20	2752	257/724	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 12:59

S21	3971	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:22
S22	509	257/731	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:42
S23	1262	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:57
S24	4429	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 13:57
S25	12	bare near (die or chip or IC) and packaged near (chip or die or IC) and Heatsink	USPAT	OR	OFF	2005/03/02 22:47
S26	15	bare near (die or chip or IC) same packaged near (chip or die or IC) same Heat	USPAT	OR	ON	2005/03/03 11:41
S27	13	bare near (die or chip or IC) with (uncapsulat\$3 or mold\$3) and packaged near (chip or die or IC) and Heat	USPAT	OR	ON	2005/03/03 12:09
S28	15	bare near (die or chip or IC or semiconductor) with (uncapsulat\$3 or mold\$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 12:11
S29	38	bare near (die or chip or IC or semiconductor) same (uncapsulat\$3 or mold\$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 12:15
S30	183	bare near (die or chip or IC or semiconductor) and (uncapsulat\$3 or mold\$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 17:39

S31	6	non-packaged near (die or chip or IC or semiconductor) and (uncapsulat\$3 or mold\$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 17:25
S32	7	(non or none) near packaged near (die or chip or IC or semiconductor) and (uncapsulat\$3 or mold\$3) and packaged near (chip or die or IC or semiconductor) and Heat	USPAT	OR	ON	2005/03/03 17:26
S33	163	bare near (die or chip or IC or semiconductor) and (uncapsulat\$3 or mold\$3) and packaged near (chip or die or IC or semiconductor) and (cover or lid)	USPAT	OR	ON	2005/03/03 18:16
S34	11	257/685 and bare near (die or chip or IC or semiconductor) same (encapsulat\$3 or mold\$3) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 18:20
S35	304	bare near (die or chip or IC or semiconductor) same (encapsulat\$3 or mold\$3) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 18:48
S36	2086	bare near (die or chip or IC or semiconductor) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:01
S37	18	bare near (die or chip or IC or semiconductor) same (encapsulat\$3 or mold\$3) and (cover or lid or heat or cap)	JPO	OR	ON	2005/03/03 18:48
S38	1782	S36 not S35	USPAT	OR	ON	2005/03/03 18:51
S39	19	(non-packaged or none-packaged or (non or none) near packaged) near (die or chip or IC or semiconductor) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:03
S40	32904	(die or chip or IC or semiconductor) with (encapsulat\$3 or mold\$3 or cover\$3 near resin) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:04
S41	462	257/685 and (die or chip or IC or semiconductor) with (encapsulat\$3 or mold\$3 or cover\$3 near resin) and (cover or lid or heat or cap)	USPAT	OR	ON	2005/03/03 21:31
S42	1	"5754410".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09

S43	1	"5757074".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09
S44	1	"6064219".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09
S45	1	"6246252".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:09
S46	1	"6246252".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:10
S47	1	"6278286".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:10
S48	1	"4410927".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:15
S49	1	"4826297".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:15
S50	1	"5040994".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S51	1	"5134546".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S52	1	"5434745".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S53	1	"5981043".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S54	1	"6380616".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:17
S55	1	"6445254".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:18
S56	1	"6545368".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:18
S57	1	"20020027763".PN.	US-PGPUB	OR	OFF	2005/03/03 21:18
S58	1	"20030071348".PN.	US-PGPUB	OR	OFF	2005/03/03 21:18
S59	4230	S40 and module	USPAT	OR	ON	2005/03/03 21:32
S60	1033	S59 and heat near sink	USPAT	OR	ON	2005/03/03 22:51
S61	1	"4699593".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:41
S62	1	"5371654".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:41
S63	1	"5384955".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S64	1	"5468681".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S65	1	"5477082".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S66	1	"5557502".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42

S67	1	"5570274".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:42
S68	1	"5594275".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S69	1	"5598033".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S70	1	"5639989".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S71	1	"5691041".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S72	1	"5796170".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S73	1	"5834848".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:43
S74	1	"5838551".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:44
S75	1	"5854534".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:44
S76	1	"5953214".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S77	1	"5977640".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S78	1	"5978229".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S79	1	"6344688".PN.	USPAT; USOCR	OR	OFF	2005/03/03 21:45
S80	1	"4151547".PN.	USPAT; USOCR	OR	OFF	2005/03/03 22:09
S81	37	heat near sink with metal near cap 257/796	USPAT	OR	ON	2005/03/03 22:51
S82	970		US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/17 18:20
S83	1260		US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/17 18:20
S84	2736	257/706	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 13:21

S85	2736	257/706	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 13:34
S86	0	S84 not S85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 12:53
S87	12	"5424573".pn. or "5616957".pn. or "5977626".pn. or "6414385". pn. or "6437984".pn. or "6608769".pn. or "6703698".pn. or "6734552".pn. or "6849940". pn. or "20010008776".pn. or "20020175421".pn. or "20020195270".pn.	US-PGPUB; USPAT	OR	OFF	2006/01/19 13:23
S88	1043	257/796	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 13:49
S89	3443	257/787	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 15:45
S90	2617	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 16:04
S91	1368	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 16:20
S92	2291	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 17:05

S93	4933	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 17:34
S94	340	257/731	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 17:45
S95	3895	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 18:24
S96	2289	257/724	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/19 18:24
S97	6	("20020195704" "5754410" "5757074" "6064219" "6246252" "6278286").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:30
S98	61818	"6630727".pn. without with (adhesive or glue)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:30
S99	0	"6630727".pn. and without with (adhesive or glue)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:35
S100	11	("20020027763" "20030071348" "4410927" "4826297" "5040994" "5134546" "5434745" "5981043" "6380616" "6445254" "6545368").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/01/20 16:34
S101	1715	wir\$3 with (chip or die or IC or semiconductor) and without with (adhesive or glue)	USPAT	OR	OFF	2006/01/20 16:40
S102	1018	S101 and (mold\$3 or encapsulat\$3)	USPAT	OR	OFF	2006/01/20 16:40
S103	9	("5365656").URPN.	USPAT	OR	OFF	2006/01/20 16:37
S104	87	wir\$3 with (chip or die or IC or semiconductor) with without with (adhesive or glue)	USPAT	OR	OFF	2006/01/20 16:52

S10 5	48	S104 and (mold\$3 or encapsulat\$3)	USPAT	OR	OFF	2006/01/20 16:41
S10 6	154	wir\$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach\$3 with without with (adhesive or glue)	USPAT	OR	ON	2006/01/20 17:05
S10 7	12	wir\$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach\$3 with directly with without with (adhesive or glue)	USPAT	OR	ON	2006/01/20 17:07
S10 8	1	wir\$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach\$3 with directly near substrate with without with (adhesive or glue)	USPAT	OR	ON	2006/01/20 17:07
S10 9	1	wir\$3 with (chip or die or IC or semiconductor) and (chip or die or IC or semiconductor) with attach\$3 with directly near substrate with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:07
S11 0	1	(chip or die or IC or semiconductor) with attach\$3 with directly near substrate with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:08
S11 1	3	(chip or die or IC or semiconductor) with attach\$3 with directly near (substrate or board\$3 or carrier or hous\$3) with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:10
S11 2	12	(chip or die or IC or semiconductor) with directly near (substrate or board\$3 or carrier or hous\$3) with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:11
S11 3	3	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly near (substrate or board\$3 or carrier or hous\$3) with without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:12
S11 4	96	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly near (substrate or board\$3 or carrier or hous\$3) and without with (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:19

S11 5	21	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly near (substrate or board\$3 or carrier or hous\$3) and without near (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:22
S11 6	98	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and without near (adhesive or glue)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:27
S11 7	77	S116 not S114	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:23
S11 8	112	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and without near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:30
S11 9	14	S118 not S116	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:28
S12 0	0	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and "not" with us\$3 near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:41
S12 1	0	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and "don't" with us\$3 near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:31
S12 2	0	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and "don't" with us\$3 with (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:32
S12 3	0	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and "not" with us\$3 with (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:32

S12 4	470	wir\$3 near bond\$3 with (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3)	USPAT	OR	ON	2006/01/20 17:32
S12 5	46	wir\$3 near bond\$3 with (chip or die or IC or semiconductor) with directly near (substrate or board\$3 or carrier or hous\$3)	USPAT	OR	ON	2006/01/20 17:33
S12 6	3	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and lack\$3 near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:43
S12 7	0	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and absent\$3 near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:43
S12 8	4	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (substrate or board\$3 or carrier or hous\$3) and absent\$3 near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:44
S12 9	145	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with (absenc\$3 or lack\$3 or without) near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:53
S13 0	1087	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with (absenc\$3 or lack\$3 or without) with (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 17:54
S13 1	80	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly with (absenc\$3 or lack\$3 or without) with (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:02
S13 2	136	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) with directly same (absenc\$3 or lack\$3 or without) with (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:09
S13 3	56	S132 not S131	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:03

S13 4	1528	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) same (absenc\$3 or lack\$3 or without) with (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:18
S13 5	1392	S134 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:19
S13 6	273	wir\$3 near bond\$3 and (chip or die or IC or semiconductor) same (absenc\$3 or lack\$3 or without) near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:22
S13 7	251	S136 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:23
S13 8	909	(chip or die or IC or semiconductor) same (absenc\$3 or lack\$3 or without) near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:22
S13 9	476	wir\$3 and (chip or die or IC or semiconductor) same (absenc\$3 or lack\$3 or without) near (adhesive or glue or underfill or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:34
S14 0	454	S139 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:34
S14 1	387	wir\$3 and (chip or die or IC or semiconductor) same (absenc\$3 or lack\$3 or without) near (adhesive or glue or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:50
S14 2	367	S141 not S132	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 18:34
S14 3	354	wir\$3 and (chip or die or IC or semiconductor) near bare with directly and (adhesive or glue or attach\$3 near material)	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 19:09
S14 4	1	"6630727".pn. and coverlayer with heat	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 19:42
S14 5	7	"5471366".pn. or "6069023".pn. or "6140144".pn. or "6316840".pn. or "6574860".pn. or "6929976".pn. or "20020025608".pn.	US-PGPUB; USPAT; JPO	OR	ON	2006/01/20 19:42